

5.3 Bill of Materials

Table 1. HPA506B Bill of Materials

-001	-002	-003	-004	RefDes	Value	Description	Size	Part Number	MFR
1	1	1	1	C1	1 µF	Capacitor, Ceramic, 25V, X5R, 10%	0603	ECJ-1VB1E105K	Panasonic
0	0	0	0	C2		Capacitor, Ceramic, 25V, X5R, 10%	0805	ECJ-2FB1E225K	Panasonic
1	1	1	1	C3	2.2 µF	Capacitor, Ceramic, 10V, X5R, 10%	0603	ECJ-1VB1A225K	Panasonic
0	0	0	0	C4		Capacitor, Ceramic, 10V, X5R, 10%	0805	ECJ-2FB1A106K	Std
0	0	0	0	C5		Capacitor, Ceramic, 10V, X5R, 10%	0603	ECJ-1VB1A225K	Panasonic
2	2	2	2	D1, D2	LTST-C190GKT	Diode, LED, Green, 2.1-V, 20-mA, 6-mcd	0603	LTST-C190GKT	Lite On
0	0	0	0	D3	BZX84C5V6-7-F	Diode, Zener, 5.6-V, 350-mW	SOT-23	BZX84C5V6-7-F	Diodes
1	1	1	1	J1	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
1	1	1	1	J2	ED555/4DS	Terminal Block, 4-pin, 6-A, 3.5mm	0.55 x 0.25 inch	ED555/4DS	OST
4	4	4	4	JMP1, JMP2, JMP4, JMP5	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
1	1	1	1	JMP3	PEC03SAAN	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3	PEC03SAAN	Sullins
1	1	1	1	R1	665	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	0	1	0	R11	50k	Potentiometer, 3/8 Cermet, Single-Turn	0.25x0.17 inch	3266W-503-LF	Bourns
0	1	0	1	R11	500k	Potentiometer, 3/8 Cermet, Single-Turn	0.25x0.17 inch	3266W-504-LF	Bourns
2	2	2	2	R2, R4	10k	Potentiometer, 3/8 Cermet, Single-Turn	0.25x0.17 inch	3266W-103-LF	Bourns
2	2	2	2	R3, R12	1.0k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	2	2	2	R5, R9	1.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
0	0	0	0	R6, R13, R14		Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	1	1	1	R7	10k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	2	2	2	R8, R10	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	0	0	0	U1	BQ24090DGQ	IC, 800mA, Single-Input, Single Cell Li-Ion BATTERY CHARGER	HTSSOP	BQ24090DGQ	TI
0	1	0	0	U1	BQ24091DGQ	IC, 800mA, Single-Input, Single Cell Li-Ion BATTERY CHARGER	HTSSOP	BQ24091DGQ	TI
0	0	1	0	U1	BQ24092DGQ	IC, 800mA, Single-Input, Single Cell Li-Ion BATTERY CHARGER	HTSSOP	BQ24092DGQ	TI
0	0	0	1	U1	BQ24093DGQ	IC, 800mA, Single-Input, Single Cell Li-Ion BATTERY CHARGER	HTSSOP	BQ24093DGQ	TI
5	5	5	5	Shunt (Note 5)		Shunt, 100-mil, Black	0.1	929950-00	3M
1	1	1	1	-		PCB, 3 In x 1.85 In x 0.0031 In		HPA506	Any

- Notes: 1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk (***) cannot be substituted. All other components can be substituted with equivalent MFG's components.
 5. Apply shunt to JMP1/2/4/5 and JMP3:2/3.

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